EEE-2103: Electronic Devices and Circuits

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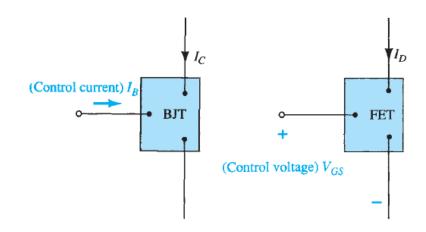
Field Effect Transistors

FET vs BJT:

FET and BJT are three-terminal devices.

BJT is current-controlled device. JFET is voltage-controlled device.

BJT $\rightarrow npn$ and pnp. JFET $\rightarrow n$ -channel and p-channel.



BJT \rightarrow bipolar device = conduction level is function of two charge carriers. FET \rightarrow unipolar device = electron (*n*-channel) or hole (*p*-channel) conduction.

Input impedance \rightarrow FET >> BJT.

Sensitivity to changes in applied signal \rightarrow BJT >> FET.

AC voltage gain \rightarrow BJT >> FET.

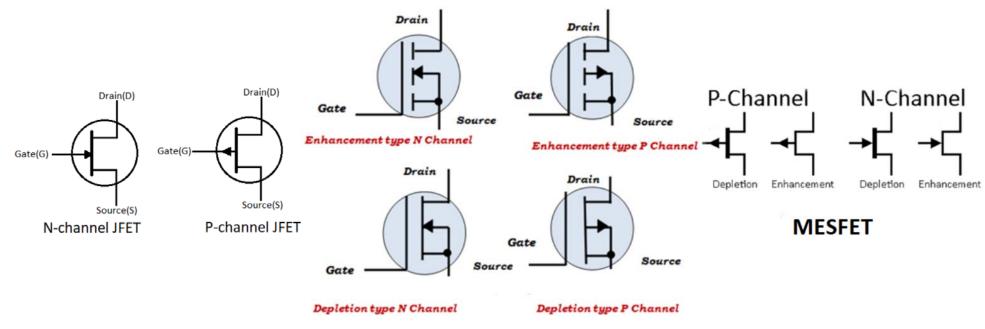
Temperature stability \rightarrow FET >> BJT.

Size \rightarrow BJT >> FET.

Field Effect Transistors

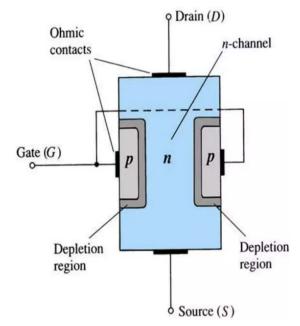
Types of FETs:

- 1) Junction field-effect transistor (JFET).
- 2) Metal-oxide-semiconductor field-effect transistor (MOSFET).
 - i) Depletion type MOSFET.
 - ii) Enhancement type MOSFET.
- 3) Metal-semiconductor field-effect transistor (MESFET).

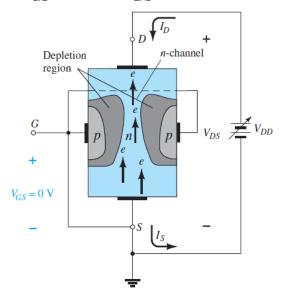


Construction of JFETs

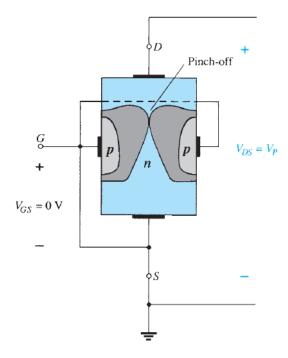
- Source → through which majority carriers enter into channel.
- Drain → through which majority carriers leave from channel.
- Gate → two internally connected heavily doped impurity region.
- Channel →
 region between source and drain.
 sandwiched between two gates.
- No-bias condition \rightarrow two p-n junctions. depletion region at each junction.

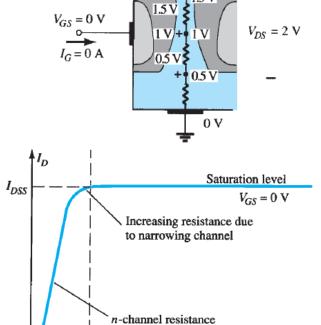


 V_{GS} = 0 V, V_{DS} = Some +ve value



Depletion region is wider near top of both p-type Reason for change in width \rightarrow $^{\circ + 2}$ $^{\circ}$





 V_{DS}

 V_P

n

 I_D does not drop off at pinch-off \rightarrow

absence of I_D = absence of different potential levels through n-channel. loss of depletion region distribution.

$$V_{DS} > V_P \rightarrow$$

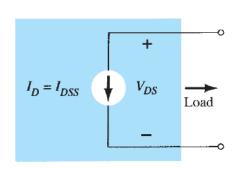
region of close encounter between two depletion regions increases in length.

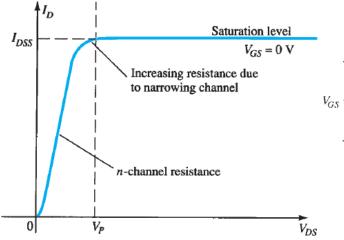
level of I_D remains same.

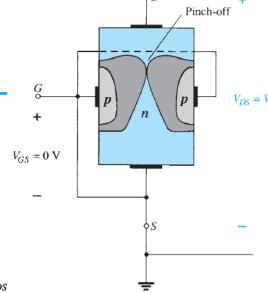
JFET = characteristics of current source.

current is fixed at $I_D = I_{DSS}$

 I_{DSS} = maximum drain current Condition = V_{GS} = 0 V and V_{DS} > $|V_P|$.







 V_{GS} < 0 V \rightarrow

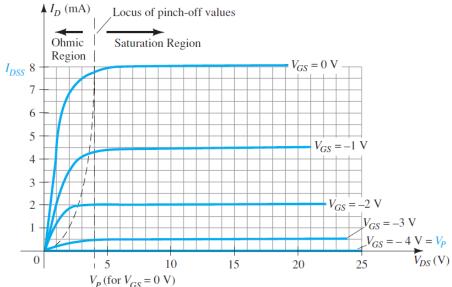
 V_{GS} is controlling voltage of JFET.

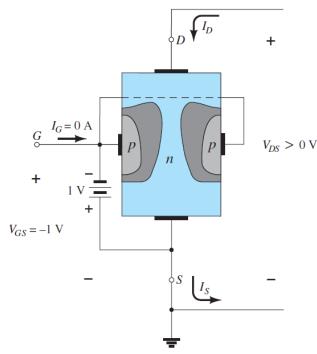
For *n*-channel, V_{GS} is made more and more -ve.

Effect of applied negative-bias →

Establish depletion regions = obtained with V_{GS} = o V at lower levels of V_{DS} .

Reach saturation level at lower level of V_{DS} .

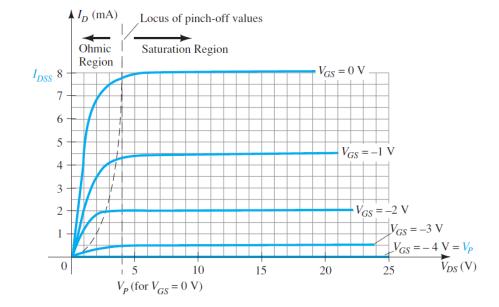




Ohmic or voltage-controlled resistance region \rightarrow JFET is employed as variable resistor. resistance is controlled by applied V_{GS} . V_{GS} becomes more and more negative = resistance level increases.

$$r_d = \frac{r_o}{(1 - V_{GS}/V_P)^2}$$
 $r_o = \text{resistance with } V_{GS} = \text{o V}$
 $r_d = \text{resistance at particular level of } V_{GS}$

For *n*-channel JFET \rightarrow $r_o = 10 \text{ k}\Omega \text{ (}V_{GS} = 0 \text{ V}, V_P = -6 \text{ V}\text{)}$ $r_d = 40 \text{ k}\Omega \text{ at } V_{GS} = -3 \text{ V}.$



Transfer characteristics = plot of I_D versus V_{GS} . Shockley's equation \rightarrow

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

 I_{DSS} , V_P = constants. V_{GS} = control variable. nonlinear relationship between I_D and V_{GS} , curve grows exponentially with decreasing $|V_{GS}|$.

